



TIF™100-12-05ES Series thermally conductive interface materials are gap fillers reinforced one side with kepton; the other side with adhesive. They are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and viscoelastic feature make them ideal to coat very uneven surfaces. Its smooth, puncture-, tear-, wear-resistant reinforcement surface is perfect for reworking and plug-in devices.

Features

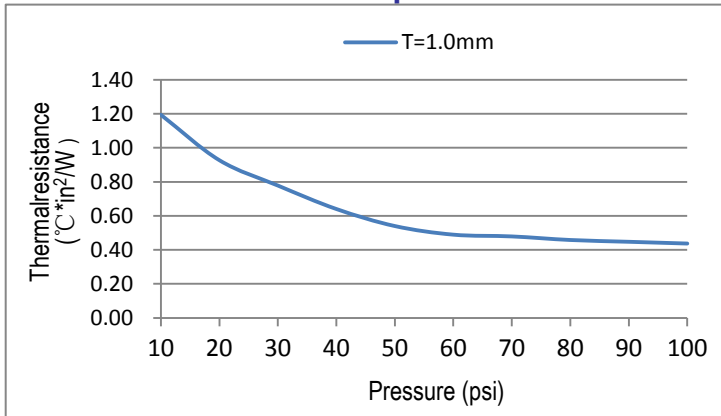
- » Naturally tacky needing no further adhesive coating
- » Soft and Compressible for low stress applications
- » Available in varies thickness

Application

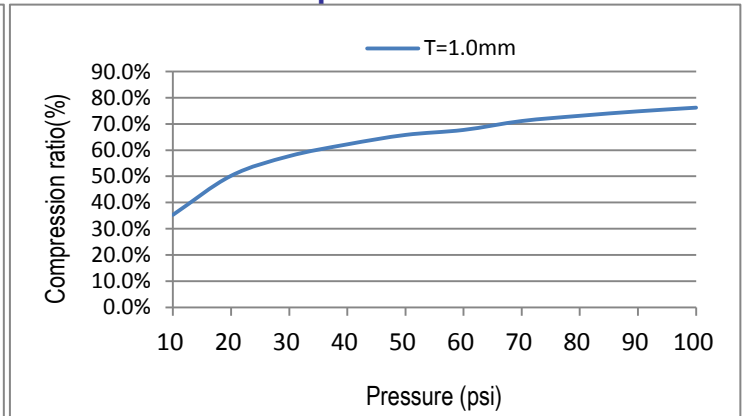
- » Cooling components to the chassis of frame
- » Set Top Box
- » Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

| Typical Properties of TIF™100-12-05ES Series | | |
|--|-----------------------------------|--------------|
| Property | Value | Test method |
| Color | Blue | Visual |
| Construction | Ceramic filled silicone elastomer | ***** |
| Thickness | 0.020"(0.5mm)~0.200"(5.0mm) | ASTM D374 |
| Hardness (Shore 00) | 12±5 | ASTM 2240 |
| Density (g/cm ³) | 2.0 | ASTM D792 |
| Operating Temp | -40~160°C | ***** |
| Dielectric Breakdown Voltage(T=1.0mm,Vac) | ≥5500 | ASTM D149 |
| Dielectric Constant@1MHz | 4.5 | ASTM D150 |
| Volume Resistivity | ≥1.0X10 ¹² Ohm-cm | ASTM D257 |
| Thermal Conductivity (W/mK) | 1.2 | ASTM D5470 |
| | 1.2 | ISO22007-2.2 |
| Flame Rating | 94 -V0 | UL E331100 |

Pressure vs. Thermal Impedance



Pressure vs . Compression Ratio



Product Thicknesses: 0.020-inch(0.5mm)to 0.200" (5.0mm) **Product Sizes:** 8" x 16"(203mm x406mm)

Individual die cut shapes and custom thickness can be supplied. Please contact us for confirming
 Safe disposal method does not require special protection. The storage condition is low temperature and dry, away from open fire and away from direct sunlight. For detailed method, please refer to the product material safety data sheet.

